

# LIDAR Technology and Applications

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# Who is Hamamatsu Photonics


## "A HIDDEN CHAMPION OF THE 21<sup>ST</sup> CENTURY"

Hermann Simon, author of the *Hidden Champions of the Twenty-First Century*

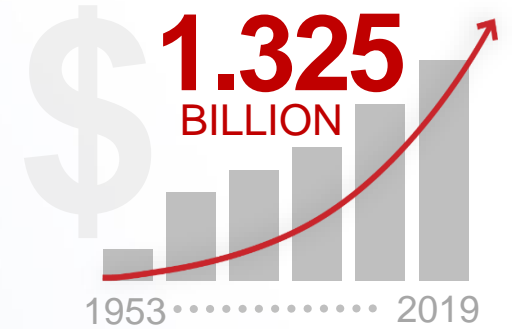
  
SINCE  
**1953**

**3**   
R&D  
CENTERS

**7**   
MANUFACTURING  
FACILITIES

**9%**   
R&D  
EXPENSE

  
**5,035**  
EMPLOYEES



**3** **NOBEL**  
**PRIZE**   
CONTRIBUTIONS

  
**15.000**  
PRODUCTS

**1995**   
ENTRY IN  
TOKYO  
**STOCK EXCHANGE**



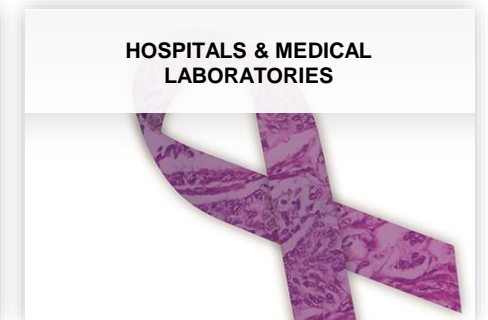
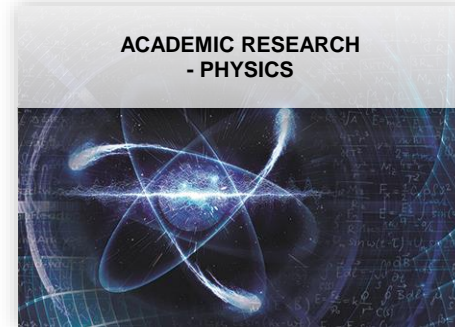
**UNITED NATIONS  
GLOBAL COMPACT**

- ✓ HUMAN RIGHTS
- ✓ LABOUR STANDARDS
- ✓ ENVIRONMENT
- ✓ ANTI-CORRUPTION

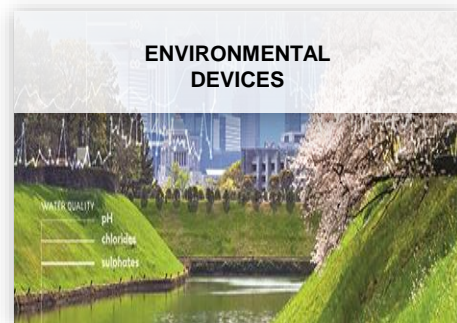
\*Figures taken in 2019

# Our diverse markets include..

## END-USERS SEGMENTS



## DEVICE SEGMENTS



# Extensive portfolio of standard and customized solutions

## TECH-POWERED SOLUTIONS

### LASERS



### MODULES



### SYSTEMS



### OPTICAL SENSORS



### CAMERAS



### OPTICAL COMPONENTS



### LIGHT & RADIATION SOURCES



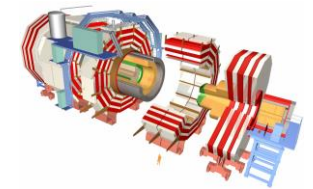
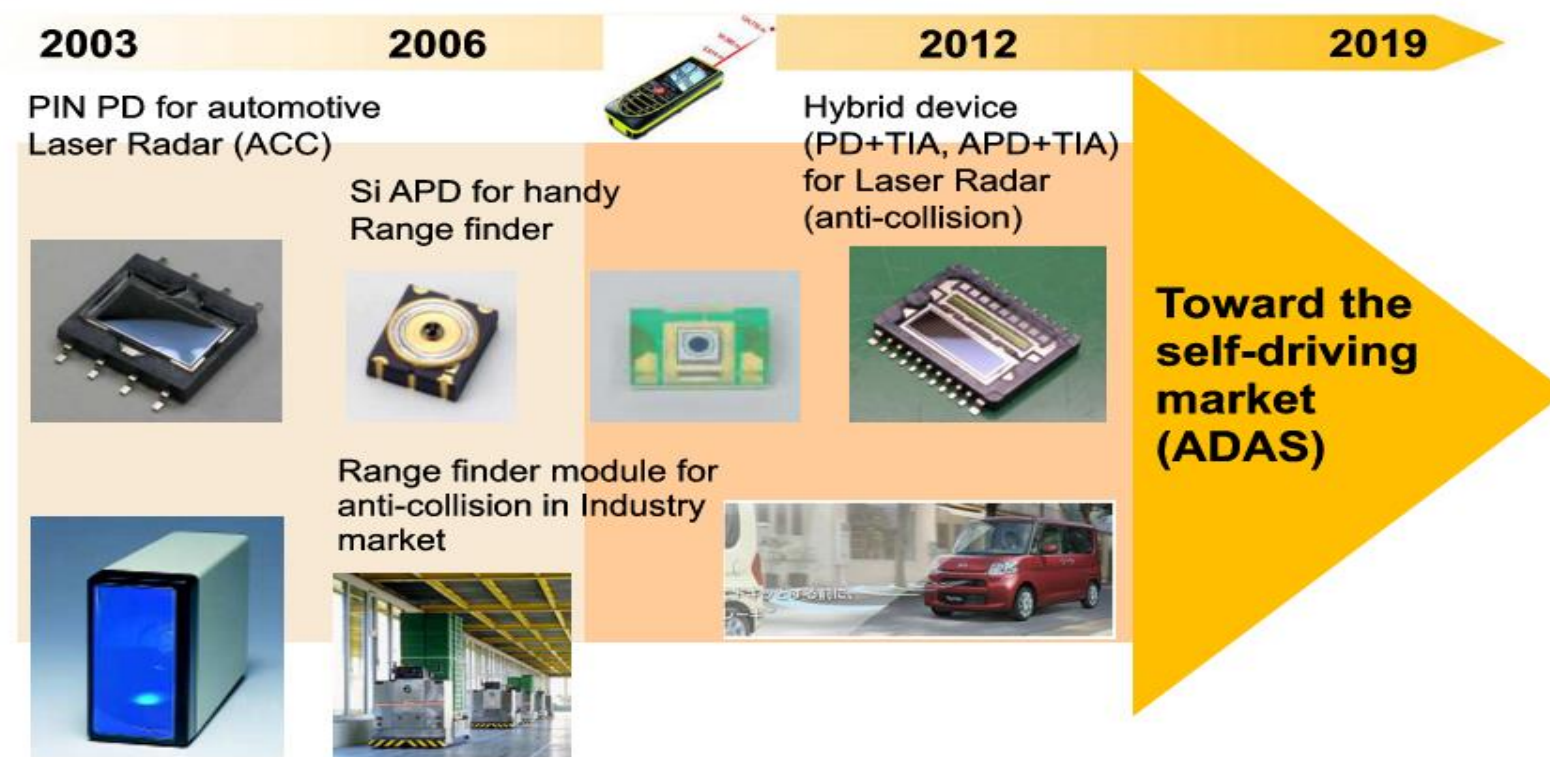
# LiDAR Focus

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# Extensive know-how in the development of core devices

- Hamamatsu Photonics has a long history, extensive experience and know-how in the development and manufacture of 'core devices' for LiDAR applications.
- We have a long and established business for LiDAR applications including automotive, industrial and more.



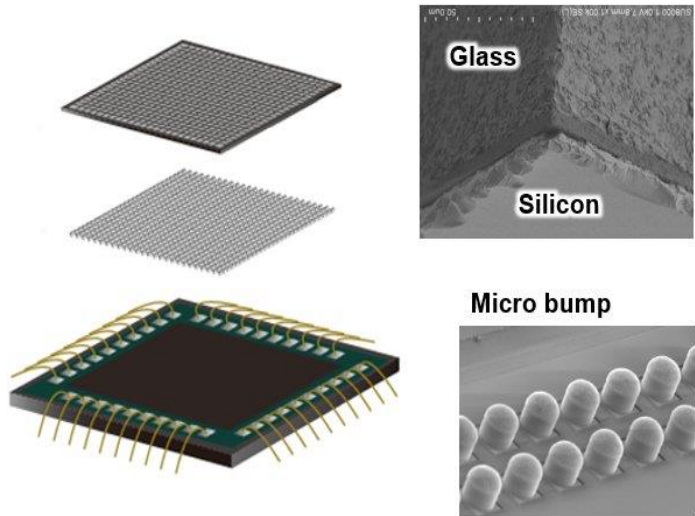
## Features

- High temperature operation
- High resistance to environment
- High speed operation



Characteristic	value
Operation temperature	-40 to +105 degC
Storage temperature	-40 to +125 degC

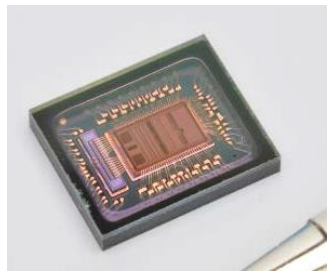
# 2D – MPPC Arrays



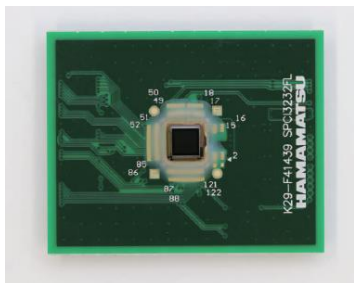
## Applied technique for MPPC and ASIC Hybrid 2D Array

- Support glass attachment
- Silicon wafer thinning < 50 $\mu$ m
- Micro bump forming
- Flip chip bonding

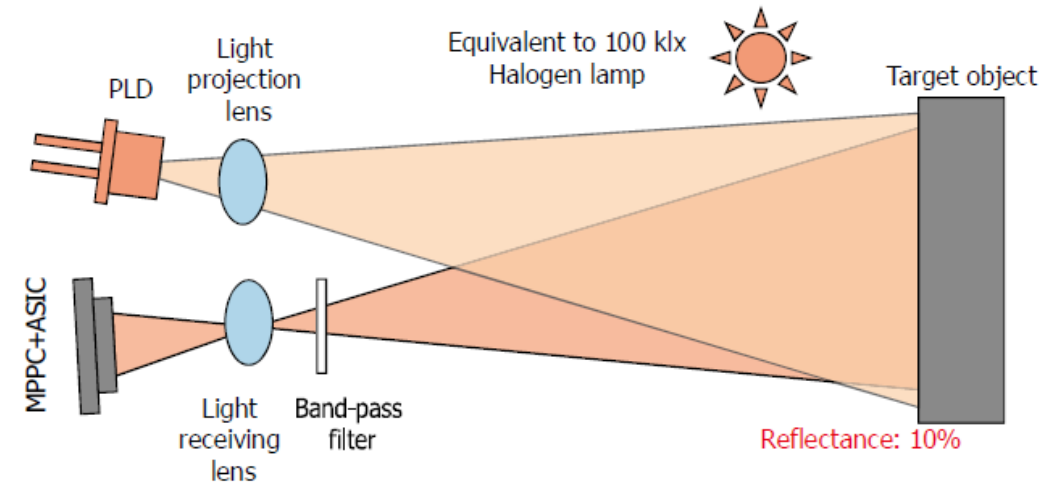
- Higher PDE, around 905 nm
- Lower Long tail
- Wider dynamic range
- 2D Array / Photon counting imaging



**1D S15088-0225GL-01**  
**Available now!**



**2D in development!**



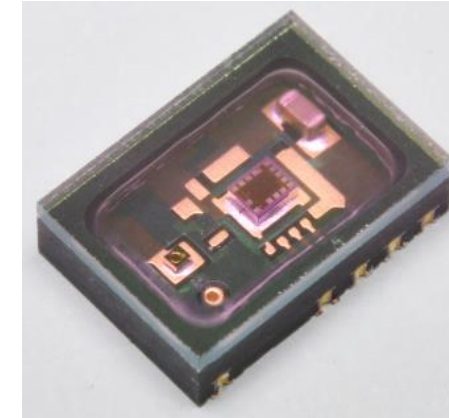


## Future products

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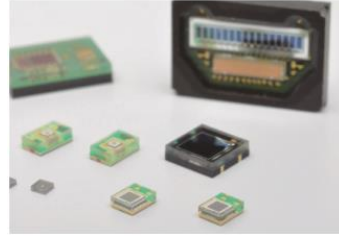
1 ch InGaAs PD and APD (array) & TIA currently in development.

- **Higher laser power availability and limited influence from sunlight**
- **Unique TIA design reducing ringing effect and temperature influence.**
- **TIA offered on same chip package as sensor**
- **Operation temp -40 to +105 degC**



**Si APD 1ch and 16 ch currently available!**

# Hamamatsu capabilities for LiDAR

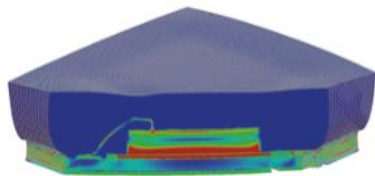


Core Device

- Detector (PD/APD/MPPC/SPAD, Si /InGaAs)
- Laser (PLD/VCSEL)
- Band Pass Filter

Reliability

- Automotive standard (AEC-Q10X)
- Simulation technology (stress/thermal simulation etc)



Capacity

- In-house front-end & back-end
- New building for higher capacity



For LiDAR

[www.hamamatsu.com](http://www.hamamatsu.com)